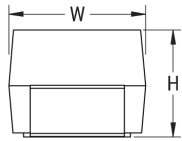
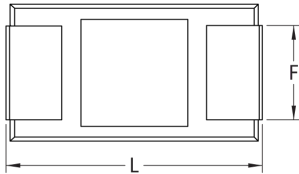
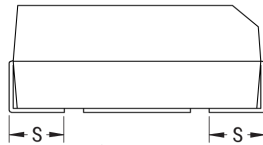


### BOTTOM VIEW



CATHODE (-) END VIEW



SIDE VIEW

Click [here](#) for the 3D model.

### Dimensions

L	24.5mm +/-0.5mm
W	8.5mm +/-0.5mm
H	9.1mm +/-0.5mm
S	3mm +/-0.3mm
F	4.2mm +/-0.5mm

### Packaging Specifications

Packaging	Bulk, Box
Packaging Quantity	100

### General Information

Series	T555
Dielectric	Polymer Tantalum
Style	SMD Chip
RoHS	No
SCIP Number	43449f08-bd3e-4b72-a04c-6ca7dd4144ff
Termination	Tin
AEC-Q200	No
Component Weight	5.54 g
Shelf Life	156 Weeks

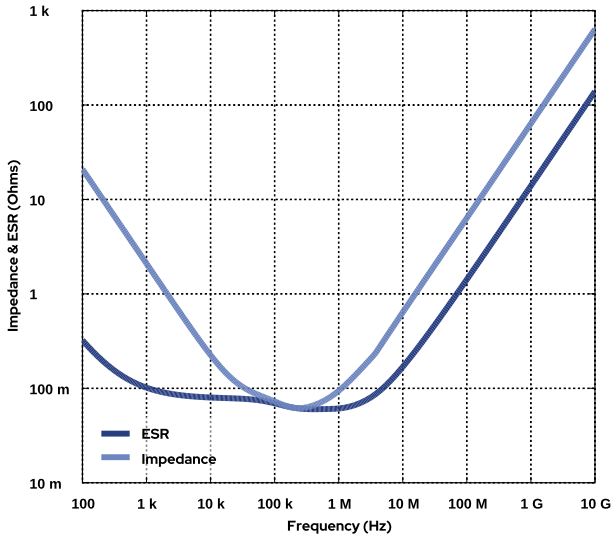
### Specifications

Capacitance	75 uF
Capacitance Tolerance	10%
Voltage DC	75 VDC, 58.5 VDC (105°C), 86.25 VDC (85°C)
Temperature Range	-55/+105°C
Life	2000 Hrs
Dissipation Factor	5% (120Hz 25C)
Failure Rate	N/A
Resistance	110 mOhm (100kHz 25C)
Ripple Current	1580 mAmps (40kHz 85C)
Leakage Current	42.2 uA (5min 25°C)
Testing and Reliability	25C +/-5C, 10 cycles, after constant voltage conditioning (KEMET standard)

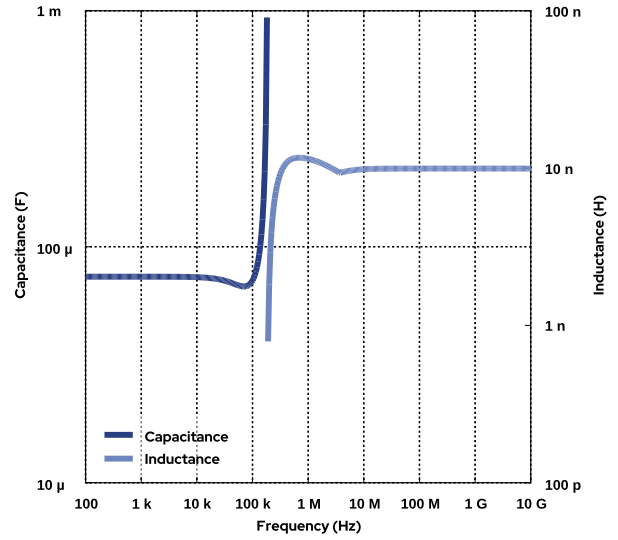
## Simulations

For the complete simulation environment please visit [K-SIM](#).

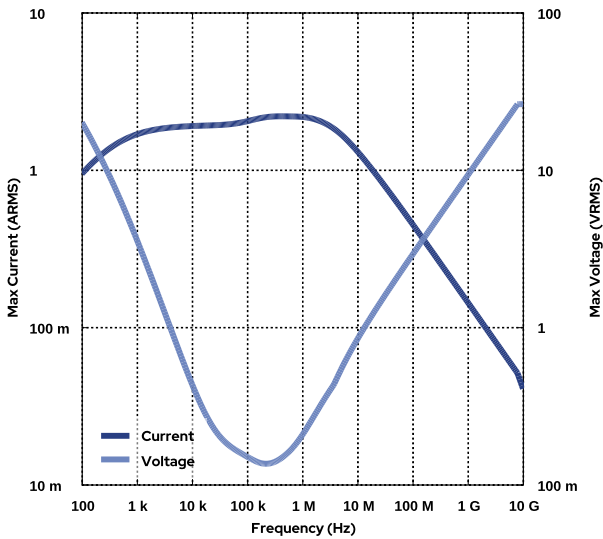
**Impedance and ESR**



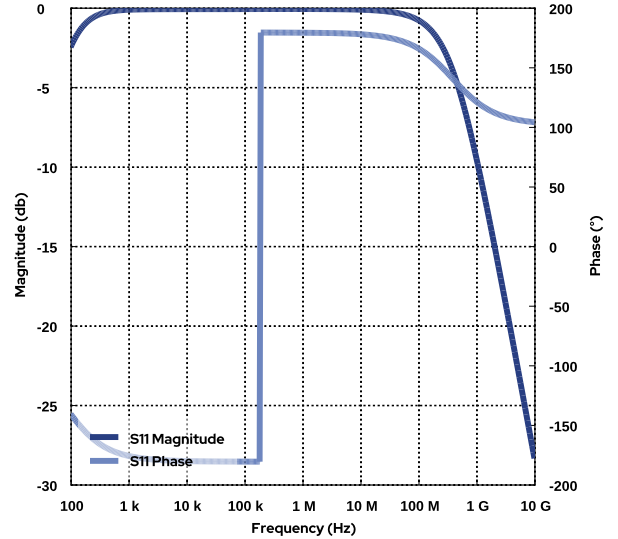
**Capacitance and Inductance**

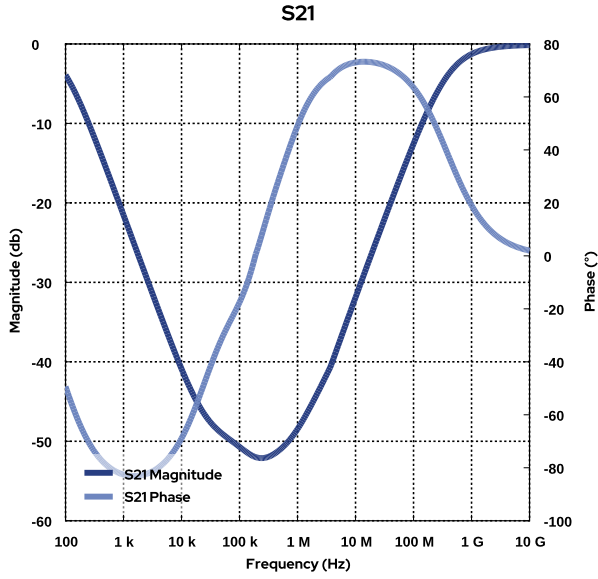


**Current and Voltage**



**S11**





**These are simulations.**

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.